Application Number 10/731,881

Amendment in response to the Office Action mailed May 24, 2007

AMENDMENTS TO THE SPECIFICATION

Please replace paragraph [0002] beginning at page 1, line 20 of the originally filed disclosure with the following amended paragraph:

[0002] The following co-pending and commonly-assigned U.S. Patent Applications, filed on
even date herewith, are also incorporated herein by reference:
1. U.S. patent application entitled "MODULAR IMPLANTABLE MEDICAL DEVICE," to
Wahlstrand et al., Ser. No. [[]] 10/731,869, assigned Attorney Docket No.: 1023-
318US01/P-10891.01, filed Dec. 9, 2003;
2. U.S. patent application entitled "IMPLANTATION OF LOW-PROFILE
IMPLANTABLE MEDICAL DEVICE," to Singhal et al., Ser. No. [[]] 10/731.868,
assigned Attorney Docket No.: 1023-330US01/P-11795.00, filed Dec. 9, 2003;
3. U.S. patent application entitled "OVERMOLD FOR A MODULAR IMPLANTABLE
MEDICAL DEVICE," to Singhal et al., Ser. No. [[]] 10/730,873, assigned Attorney
Docket No.: 1023-332US01/P-11798.00, filed Dec. 9, 2003;
4. U.S. patent application entitled "COUPLING MODULE FOR A MODULAR
IMPLANTABLE MEDICAL DEVICE," to Janzig et al., Ser. No. [[]] 10/731,699,
assigned Attorney Docket No.: 1023-331US01/P-11796.00, filed Dec. 9, 2003;
5. U.S. patent application entitled "LEAD INTERCONNECT MODULE OF A MODULAR
IMPLANTABLE MEDICAL DEVICE," to Singhal et al., Ser. No. [[]] 10/730.878,
assigned Attorney Docket No.: 1023-334US01/P-11799.00, filed Dec. 9, 2003;
6. U.S. patent application entitled "LOW PROFILE IMPLANTABLE MEDICAL
DEVICE," to Janzig et al., No. [[]] 10/730,877, assigned Attorney Docket No.: 1023-
335US01/P-11801.00, filed Dec. 9, 2003;
7. U.S. patent application entitled "CONCAVITY OF A IMPLANTABLE MEDICAL
DEVICE AND MODULES THEREOF," to Wahlstrand et al., Ser. No. [[]] 10/731,867,
(Attorney assigned Attorney Docket No.: 1023-336US01/P-11800.00, filed Dec. 9, 2003; and
8. U.S. patent application entitled "MODULAR IMPLANTABLE MEDICAL DEVICE," to
Wahlstrand et al., Ser. No. [[]] 10/731,638, assigned Attorney Docket No.: P-20542.00,
filed Dec. 9, 2003.

Application Number 10/731,881

Amendment in response to the Office Action mailed May 24, 2007

Please replace paragraph [0035] of the originally filed disclosure with the following amended paragraph:

[0035] Control module 210 includes control electronics for controlling the monitoring and/or therapy delivery functions of modular implantable medical device 201, such as a microprocessor, and may include therapy delivery circuitry. A housing of control module 210 may be hermetic in order to protect the control electronics therein, and in embodiments is formed of a rigid material, such as titanium, stainless steel, or a ceramic. Power source module 211 includes a power source that provides energy to control module 210, which in some embodiments is a rechargeable power source such as a rechargeable battery and/or capacitor. Recharge module 212 includes a recharge coil for inductively receiving energy to recharge a rechargeable power source within power source module 211. Additional details regarding modules 210, 211 and 212, additional or alternative modules for a modular implantable medical device, may be found in commonly assigned U.S. Patent Application entitled "MODULAR IMPLANTABLE MEDICAL DEVICE," assigned Attorney Docket No.: 1023-318US01/P-10891.00; commonly assigned U.S. Patent Application entitled "COUPLING MODULES OF A DISTRIBUTED MODULAR IMPLANTABLE MEDICAL DEVICE," assigned Attorney Docket No.: 1023-333US01/P-11796.00; and commonly assigned U.S. Patent Application entitled "LEAD INTERCONNECT MODULE OF A MODULAR IMPLANTABLE MEDICAL DEVICE," assigned Attorney Docket No.: 1023-334US01/P-11799.00.